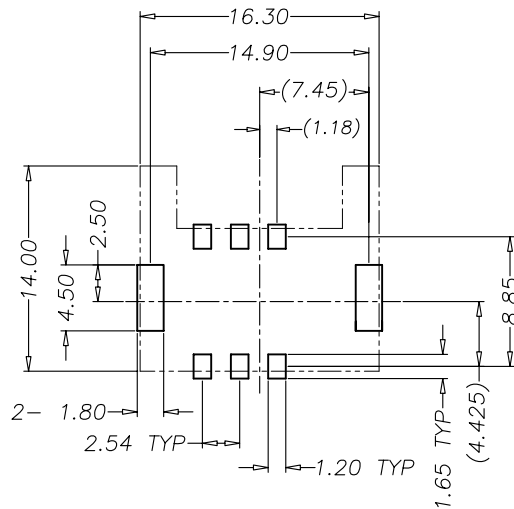
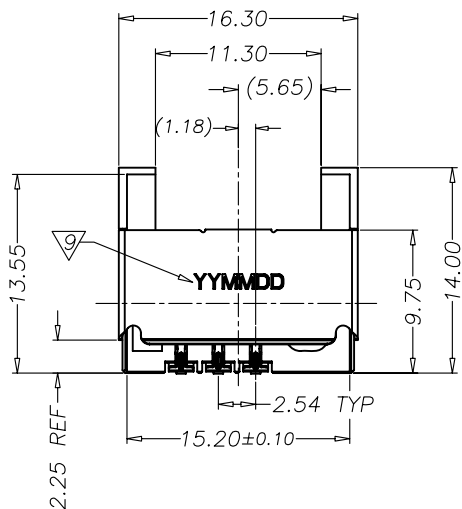
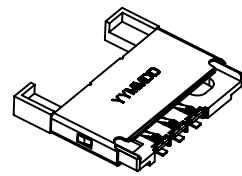


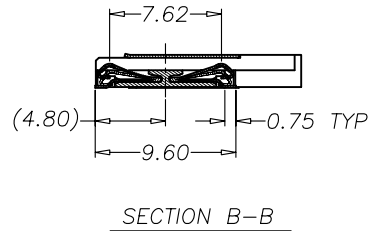
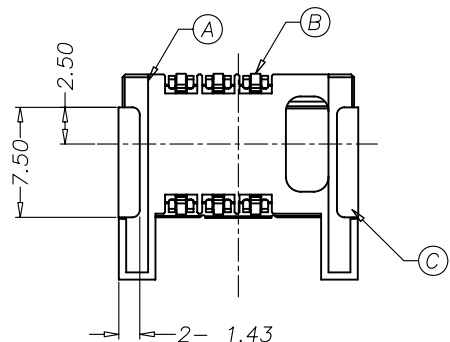
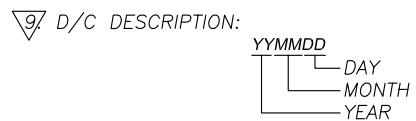
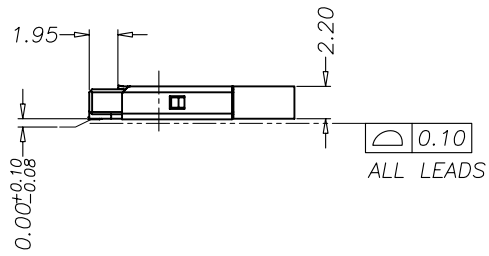
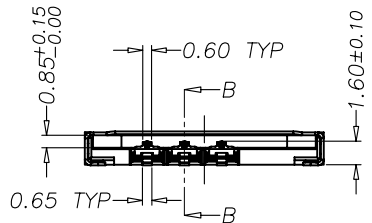
REV.	ECN NO OR DESCRIPTION	REVISED	DATE
A	PRODUCT RELEASE	R.YUAN	12/26'07



RECOMMENDED PCB LAYOUT
TOL ±0.05, TOP VIEW



- NOTE:
- MATERIAL:
HOUSING: HIGE TEMP. THERMOPLASTIC, UL94V-0, COLOR BLACK.
CONTACT: COPPER ALLOY, T=0.15mm;
SHELL: STAINLESS STEEL, T=0.20mm.
 - FINISH:
CONTACT:
15u" MIN GOLD PLATING ON CONTACT AREA;
1u" MIN GOLD PLATING ON SOLDER TAILS;
50u"~180u" NICKEL UNDERPLATING OVERALL.
SHELL:
1u" MIN GOLD PLATING ON SOLDER TAILS;
50u"~180u" NICKEL UNDERPLATING OVERALL.
 - SPECIFICATION: SEE "SIM CARD 2.2mm HEIGHT PRODUCT SPEC.".
 - SOLDER HEAT RESISTANCE: REFLOW SOLDERING 260° FOR 10 SEC.
 - TO CONFORM TO THE SINGATRON HSF SPECIFICATION.
 - GREEN PRODUCT IDENTIFICATION IN PACKING: **G.P.PASS**
 - FOR REFLOW SOLDERING LEED FREE PROCESS.
 - P/N DESCRIPTION:
2SM2002-001511
PACKAGE: TAPE AND REEL
HOUSING COLOR: BLACK
CONTACT FINISH: 15u" MIN GOLD



C	SHELL	1	SEE NOTES	SEE NOTES
B	CONTACT	6	SEE NOTES	SEE NOTES
A	HOUSING	1	SEE NOTES	COLOR BLACK
NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
UNLESS OTHERWISE SPECIFIED TOLERANCES			Singatron Electronic(Chung-Shan) Co., Ltd. 信音電子(中山)有限公司	
DECIMALS:		TITLE SIM CARD 2.2H		
ANGLES:		DWN R.YUAN 12/26'07 PART NO. 2SM2002-001511		
X	±0.5	X	±2°	CHKD ZK.CHEN 12/26'07 SCALE: 2/1 UNIT: mm
X.X	±0.3	X.X	±1°	APVD SEAN 12/26'07 SIZE: A3 SHEET: 1 OF 1 REV: A
X.XX	±0.2	CUSTOMER COPY		